

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6,759,739".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:29
L2	75410	((bump ball bumped) with (pad terminal electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:30
L3	11623	(protrude protruding protruded external exposed expose exposing bulge bulging bulged) with ((bump ball bumped) with (pad terminal electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:31
L4	12039	(protrude protruding protruded external exposed expose exposing bulge bulging bulged) with ((bump ball bumped) with (pad terminal electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:31
L5	4997	(substrate board ccarrier multilayer multi ((printed circuit wiring circuitry) adj4 board)) with 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:32
L6	3362	(chip flipchip bga die dice semiconductor electronic ic (integrated adj circuit)) with 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:34
L7	362	(frame sheet reinforce reinforcing reinforced inforcing force inforced) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:35
L8	362	(frame sheet reinforce frame reinforcing reinforced inforcing force inforced) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 12:35